

# PATENT ASSIGNMENT

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<b>SUBMISSION TYPE:</b>	NEW ASSIGNMENT
<b>NATURE OF CONVEYANCE:</b>	ASSIGNMENT
<b>CONVEYING PARTY DATA</b>	
<b>Name</b>	<b>Execution Date</b>
Tatsumi Kusaba	10/12/2005
Hidehiko Okuda	10/12/2005
<b>RECEIVING PARTY DATA</b>	
<b>Name:</b>	SUMCO CORPORATION
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<b>City:</b>	Tokyo
<b>State/Country:</b>	JAPAN
<b>PROPERTY NUMBERS Total: 1</b>	
<b>Property Type</b>	<b>Number</b>
<b>Application Number:</b>	12427442
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<b>NAME OF SUBMITTER:</b>	E. Rico Hernandez
<b>Total Attachments: 1</b> source=Assignment#page 1.tif	

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**PATENT**  
**REEL: 022574 FRAME: 0659**

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Pillsbury Winthrop LLP  
Intellectual Property Group  
P.O. Box 10500  
McLean, VA 22102

USA Patent Appln.  
Sole or Joint

For Inventions made outside USA  
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Atty. Dkt. P

M#

Client Ref.

NONPROVISIONAL

ASSIGNMENT  
OF NONPROVISIONAL APPLICATION

NONPROVISIONAL

In consideration of the sum of Ten Dollars (\$10.00) and other good and valuable consideration paid to each of the undersigned, to wit:

INSERT  
NAME(S) OF  
INVENTOR(S)

(1) Tatsumi KUSABA	(2) Hidehiko OKUDA
(3)	(4)
(5)	<input type="checkbox"/> x box If continued on page 2

the receipt and sufficiency of which are hereby acknowledged by the undersigned who at the request of, hereby sell(s), assign(s) and transfer(s) unto:

INSERT  
NAME(S) OF  
ASSIGNEE(S)  
& ADDRESS(ES)

~~SUMCO CORPORATION~~ Corporation  
of 2-1, Shibaura 1-chome, Minato-ku, Tokyo, Japan

(hereinafter designated "ASSIGNEE") the entire right, title and interest for the United States of America as defined in 35 U.S.C. 100, in the invention and all applications including any and all divisions, continuations, substitutes, and reissues thereof; and all resulting patents, known as

TITLE OF  
INVENTION

P-TYPE SILICON WAFER AND METHOD FOR HEAT-TREATING THE SAME

for which the undersigned executed an application for Letters Patents of the United States of America:

NOTE → →

(Complete

line A, B and/or C)

(A) ☐ even date herewith

(B) ☐ on

(C) ☒ in U.S. Appln. No. 11 / 200,233 filed August 10, 2005

AND the undersigned hereby authorize(s) and request(s) the United States Commissioner of Patents and Trademarks to issue said Letters Patent to the said ASSIGNEE, for its interest as ASSIGNEE, its successors, assigns and legal representatives; the undersigned agree(s) that the attorney of record in said application shall hereinafter act on behalf of said ASSIGNEE;

AND the undersigned hereby agree(s) to testify and execute any papers for ASSIGNEE, its successors, assigns and legal representatives, deemed essential by ASSIGNEE to ASSIGNEE'S full protection and title in and to the invention hereby transferred.

NOTE → → The undersigned hereby authorize(s) Pillsbury Winthrop LLP of the above address to insert hereon any further identification necessary or desirable for recordation of this document.

INVENTORS

1): Tatsumi Kusaba  
Name: Tatsumi KUSABA  
2): Hidehiko Okuda  
Name: Hidehiko OKUDA  
3): \_\_\_\_\_  
Name: \_\_\_\_\_  
4) Name: \_\_\_\_\_  
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5) Name: \_\_\_\_\_  
Name: \_\_\_\_\_

DATE SIGNED

Oct. 12, 2005

Oct. 12, 2005

WITNESSES

Shihiko Endo  
Shihiko Endo